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(54) **Title:** SYSTEMS AND METHODS OF FORMING A BRUSH TO CLEAN A SURFACE

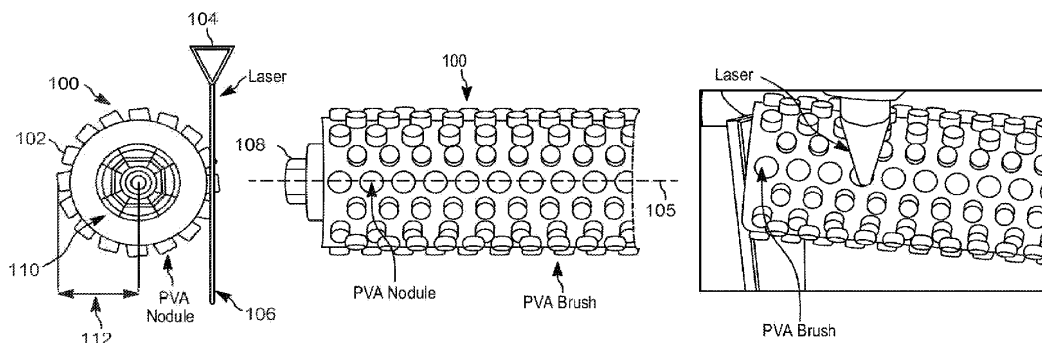


FIG. 1

(57) **Abstract:** Systems and methods of forming a brush for advanced semiconductor contact cleaning applications are disclosed. For example, a contact surface or surfaces, such as a nodule, of a brush can be cut by a laser cutting system. The use of a laser cutting system allows for uniform cutting of the contact surface across a length of the brush.

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